

OXYGEN PLASMA CLEANING

What We Offer

Design &
Simulation



Prototyping &
Fabrication



Testing &
Characterization



Oxygen plasma cleaning is a plasma-based surface treatment that effectively removes organic contaminants using reactive oxygen species, improving surface cleanliness and wettability without damaging the substrate. It is widely used in micro- and nanofabrication to enhance adhesion or clean samples prior to processes such as deposition or lithography.

Key applications

**Photoresist and polymer
residue removal
after lithography**

**Surface activation for
improved adhesion
(deposition, bonding)**

**Cleaning of
semiconductor wafers
and microdevices**

Pico Diener electronic Plasma-Surface-technology

- Working pressure: 150 mTorr – 750 mTorr
- Process gases: O₂
- Plasma generator: up to 300 W
- Gas flow up to 100 sccm
- Two operation modes: fixed pressure or fixed gas flow
- Chamber size: 120 × 75 × 290 mm (W × H × D)

Cleanroom class: ISO7

Contact person:

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PDC-002 Harrick Plasma

- Working pressure: 500 mTorr
- Process gases: O₂, N₂
- Maximum plasma power: 30 W
- Adjustable plasma power setting: (Low, Medium, High)
- Chamber size: 150 × 100 × 165 mm (W × H × D)

Cleanroom class: ISO5

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Tergeo-Plus Tabletop Plasma System PIE Scientific

- Adjustable plasma generator power: 75 W – 150 W
- The ultimate pressure of the vacuum pump < 10 mTorr
- Gas flow up to 100 sccm
- Maximum sample size: less than 160 × 280 mm (up to 6" wafer)

Cleanroom class: ISO5

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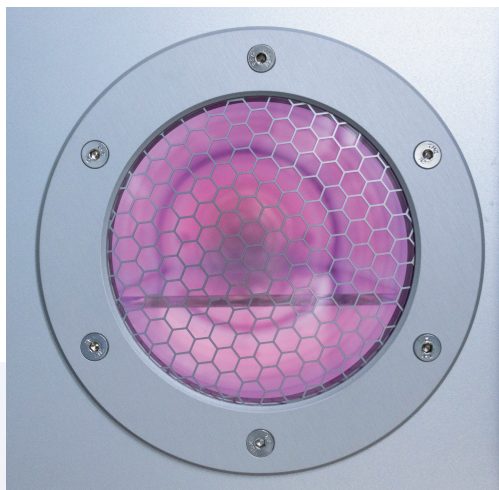
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Features:

- Continuous or pulsed plasma modes
- The ability to use plasma for direct (immersion) mode or remote (downstream) mode
- Ability to create and save recipes for different cleaning procedures
- User friendly interface

Capabilities:

- Highly effective cleaning of samples and surfaces
- Removal of photoresist and polymer residues
- Surface activation and modification



If you have any questions, please contact us by email:
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